



CALL FOR PAPERS

2021 The 6th International Conference on Mechanical and Electronics Engineering is to be held in Osaka, Japan during May 10-12, 2021

ICMEE 2021 is the premier forum for the presentation of new advances and research results in the fields of theoretical, experimental, and applied Mechanical and Electronics Engineering. The conference will bring together leading researchers, engineers and scientists in the domain of interest from around the world.

Accepted papers can be published in **ICMEE IOP proceedings, Materials Science** and Engineering and indexed by **Scopus** etc

Important Dates

Paper Submission Deadline: Jan. 05, 2021

Notification of Paper Acceptance: Jan. 25, 2021

Registration Deadline: Feb. 10, 2021

Submission Methods

1. Send your manuscript directly to conference official email: icmee@outlook.com
2. Submit your paper through easychair system: <http://confsys.iconf.org/submission/icmee2021>

Contact Ways

Ms. Serene Lo
icmee@outlook.com
+86-028-83208181

Conference Committee

Advisory Chair

Piuri Vincenzo, University of Milan

Conference Chairs

John Mo, Royal Melbourne Institute of Technology

Shih-Chieh Lin, National Tsing-Hua University

Program Chairs

Xingjian Jing, The Hong Kong Polytechnic University

Yu-Liang Chen, National Defense University

Web Chair

Renne.Gao, Science and Engineering Institute

...

Scopes

The works that will be presented and published at conference will focus on, but are not limited to, the following topics:

Mechanical Engineering

Aerodynamics Material Engineering

Automation, Mechatronics and Robotics

Mechanical Design

Automobiles Mechanical Power Engineering

Automotive Engineering Mechatronics

Ballistics MEMS and Nano Technology

Biomechanics Multibody Dynamics

...

More Topics Please Visit:

<http://www.icmee.org/cfp.html>